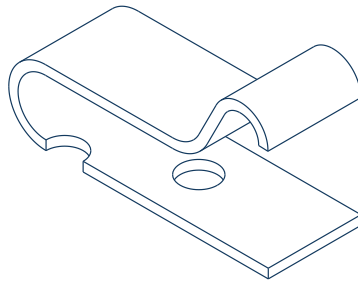




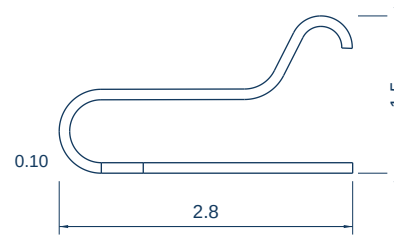
Type U-01 BU01-10028015

SMD EMI Spring Contact | Beryllium Copper | Units: mm

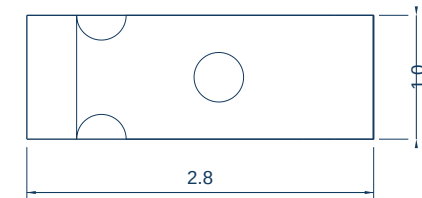
Isometric



Front view (mm)



Top view (mm)



MECHANICAL

VALUE

Thickness	0.10 mm
Width	1.0 mm +/- 0.2
Length	2.8 mm +/- 0.2
Height	1.5 mm +/- 0.2
Form	U-form: base land, 180 deg end fold, upper arm, S-rise, down-turned hook
Base land	2.40 mm flat SMD land
End fold	R0.352 / R0.349 CL, 180 deg total
Upper arm / rise	1.37 mm flat + R0.369 CL 63 deg + 0.41 mm at 63 deg
Crest / hook	R0.243 CL 61 deg / R0.248 CL 95 deg
Land hole	dia 0.40 mm at 1.55 mm, on the width centreline (estimated)
Land dent	R0.20 round scallop per side, 0.20 deep x 0.40 long, at the fold end
Developed length	6.35 mm
Material / plating	BeCu, Gold-plated (G)
Volume / mass	0.610 mm ³ 5.1 mg (BeCu)

PRODUCT DATA

VALUE

Mfr P/N	BU01-10028015G-SY (Au)
Brand	Seyunda
Description	SMD EMI Contact 2.8x1.0x1.5mm Au
Packaging	Tape & Reel (TR)
Category	Connectors, Interconnects
Sub-category	Contacts, Spring Loaded (Pogo Pins), and Pressure
Lifecycle / origin	Active / Taiwan, Republic of China
RoHS / REACH	RoHS3 Compliant / REACH Unaffected
ECCN / ESD	EAR99 / Static sensitive: Yes
Datasheet	seyunda.com/datasheet/Seyunda-SMD-Spring-Contacts-Datasheet.pdf
Product page	seyunda.com/type-u-01.html
File format	STEP AP214